



Product Change Notification: CENO-02FNXL290

Date:

22-Jun-2026

Product Category:

Motor Control Sips

Notification Subject:

CCB 7105 Final Notice: Qualification of CVB715BUA as a new mold compound material for selected dsPIC33CDVC256MP506 and dsPIC33CDVC128MP506 device families available in 64L VGQFN (9x9x0.927) package.

Affected CPNs:

[CENO-02FNXL290_Affected_CPN_06222026.pdf](#)

[CENO-02FNXL290_Affected_CPN_06222026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CVB715BUA as a new mold compound material for selected dsPIC33CDVC256MP506 and dsPIC33CDVC128MP506 device families available in 64L VGQFN (9x9x0.927) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	No
Wire Material	CuPdAu	CuPdAu	No

Die Attach Material	8600		8600		No
Molding Compound Material	G700LTD	CVB715BT	G700LTD	CVB715BUA	Yes
Lead-Frame Material	EFTEC-64T		EFTEC-64T		No
	See Pre and Post Change for comparison				

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CVB715BUA as a new molding compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 June 2026 (date code: 2624)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	December 2024					>	February 2026				June 2026				
Work Week	49	50	51	52	01		06	07	08	09	23	24	25	26	27
Initial PCN Issue Date		X													
Qual Report Availability														X	
Final PCN Issue Date									X						
Estimated Implementation Date										X					

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: December 10, 2024: Issued initial notification.

February 19, 2026: Issued final notification. Provided estimated first ship date to be on February 27, 2026. Added column "Change (Yes/No)" in the pre and post change table. Updated parts list to include

DSPIC33CDV128MP206-E/M9, DSPIC33CDV128MP206-H/M9, DSPIC33CDV128MP206-H/M9VAO, DSPIC33CDV128MP206-I/M9, DSPIC33CDV128MP206T-E/M9, DSPIC33CDV128MP206T-H/M9, DSPIC33CDV128MP206T-I/M9, DSPIC33CDV128MP506-E/M9, DSPIC33CDV128MP506-E/M9VAO, DSPIC33CDV128MP506-H/M9, DSPIC33CDV128MP506-H/M9VAO, DSPIC33CDV128MP506-I/M9, DSPIC33CDV128MP506T-E/M9, DSPIC33CDV128MP506T-E/M9VAO, DSPIC33CDV128MP506T-H/M9VAO, DSPIC33CDV128MP506T-I/M9, DSPIC33CDV256MP206-E/M9, DSPIC33CDV256MP206-E/M9VAO, DSPIC33CDV256MP206-H/M9, DSPIC33CDV256MP206-H/M9VAO, DSPIC33CDV256MP206-I/M9, DSPIC33CDV256MP206T-E/M9, DSPIC33CDV256MP206T-E/M9VAO, DSPIC33CDV256MP206T-H/M9, DSPIC33CDV256MP206T-H/M9VAO, DSPIC33CDV256MP206T-I/M9, DSPIC33CDV256MP506-E/M9, DSPIC33CDV256MP506-H/M9, DSPIC33CDV256MP506-H/M9VAO, DSPIC33CDV256MP506-I/M9, DSPIC33CDV256MP506T-E/M9, DSPIC33CDV256MP506T-H/M9VAO, DSPIC33CDV256MP506T-I/M9, DSPIC33CDV64MC106-E/M8, DSPIC33CDV64MC106-E/M8VAO, DSPIC33CDV64MC106-H/M8, DSPIC33CDV64MC106-H/M8VAO, DSPIC33CDV64MC106-I/M8, DSPIC33CDV64MC106T-E/M8, DSPIC33CDV64MC106T-E/M8VAO, DSPIC33CDV64MC106T-H/M8, DSPIC33CDV64MC106T-H/M8VAO, DSPIC33CDV64MC106T-I/M8, DSPIC33CDVC128MP506-H/M9VAO, DSPIC33CDVL64MC106-E/M8, DSPIC33CDVL64MC106-E/M8VAO, DSPIC33CDVL64MC106-H/M8, DSPIC33CDVL64MC106-H/M8VAO, DSPIC33CDVL64MC106-I/M8, DSPIC33CDVL64MC106T-E/M8, DSPIC33CDVL64MC106T-E/M8VAO, DSPIC33CDVL64MC106T-H/M8, DSPIC33CDVL64MC106T-H/M8VAO and DSPIC33CDVL64MC106T-I/M8 catalog part numbers (CPN).

June 22, 2026: Re-issued final notification to attach the Qualification Report. Update the timetable summary for Qual Report availability.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CENO-02FNXL290_Pre and Post Change Summary.pdf](#)
[PCN_CENO-02FNXL290_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

DSPIC33CDVL64MC106-E/M8
DSPIC33CDVL64MC106-E/M8VAO
DSPIC33CDVL64MC106-H/M8
DSPIC33CDVL64MC106-H/M8VAO
DSPIC33CDVL64MC106-I/M8
DSPIC33CDV128MP206-E/M9
DSPIC33CDV128MP206-H/M9
DSPIC33CDV128MP206-H/M9VAO
DSPIC33CDV128MP206-I/M9
DSPIC33CDV128MP506-I/M9
DSPIC33CDV128MP506T-E/M9
DSPIC33CDV128MP506-E/M9VAO
DSPIC33CDV128MP506-H/M9
DSPIC33CDV128MP506-H/M9VAO
DSPIC33CDV128MP506T-H/M9VAO
DSPIC33CDV128MP506T-I/M9
DSPIC33CDV256MP206-E/M9
DSPIC33CDV256MP206-E/M9VAO
DSPIC33CDV64MC106T-E/M8
DSPIC33CDV64MC106T-E/M8VAO
DSPIC33CDV64MC106T-H/M8
DSPIC33CDV64MC106T-H/M8VAO
DSPIC33CDV64MC106T-I/M8
DSPIC33CDVC128MP506-E/M9
DSPIC33CDVC128MP506-E/M9VAO
DSPIC33CDVC128MP506-H/M9
DSPIC33CDVC128MP506-H/M9VAO
DSPIC33CDVC256MP506T-I/M9
DSPIC33CDV256MP206-H/M9
DSPIC33CDV256MP206-H/M9VAO
DSPIC33CDV256MP206-I/M9
DSPIC33CDVL64MC106T-E/M8

DSPIC33CDVL64MC106T-E/M8VAO

DSPIC33CDV256MP206T-E/M9

DSPIC33CDV256MP206T-E/M9VAO

DSPIC33CDV256MP206T-H/M9

DSPIC33CDV256MP206T-H/M9VAO

DSPIC33CDV256MP206T-I/M9

DSPIC33CDV128MP206T-I/M9

DSPIC33CDV128MP506-E/M9

DSPIC33CDVL64MC106T-H/M8

DSPIC33CDVL64MC106T-H/M8VAO

DSPIC33CDVL64MC106T-I/M8

DSPIC33CDV128MP206T-E/M9

DSPIC33CDV128MP206T-H/M9

DSPIC33CDV256MP506-E/M9

DSPIC33CDV256MP506-H/M9

DSPIC33CDV256MP506-H/M9VAO

DSPIC33CDV256MP506-I/M9

DSPIC33CDV256MP506T-E/M9

DSPIC33CDV256MP506T-H/M9VAO

DSPIC33CDV256MP506T-I/M9

DSPIC33CDV64MC106-E/M8

DSPIC33CDV64MC106-E/M8VAO

DSPIC33CDV64MC106-H/M8

DSPIC33CDV64MC106-H/M8VAO

DSPIC33CDV64MC106-I/M8

DSPIC33CDVC128MP506-I/M9

DSPIC33CDVC128MP506T-E/M9

DSPIC33CDVC128MP506T-E/M9VAO

DSPIC33CDVC128MP506T-I/M9

DSPIC33CDVC256MP506-E/M9

DSPIC33CDVC256MP506-E/M9VAO

DSPIC33CDVC256MP506-H/M9

DSPIC33CDVC256MP506-H/M9VAO

DSPIC33CDVC256MP506-I/M9

DSPIC33CDVC256MP506T-E/M9

DSPIC33CDVC256MP506T-E/M9VAO

DSPIC33CDVC256MP506T-H/M9

DSPIC33CDVC256MP506T-H/M9VAO

DSPIC33CDV128MP506T-E/M9VAO

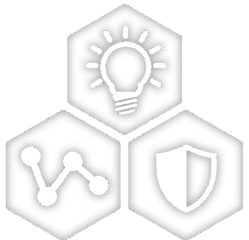
CCB 7105

Pre and Post Change Summary

PCN #: CENO-02FNXL290

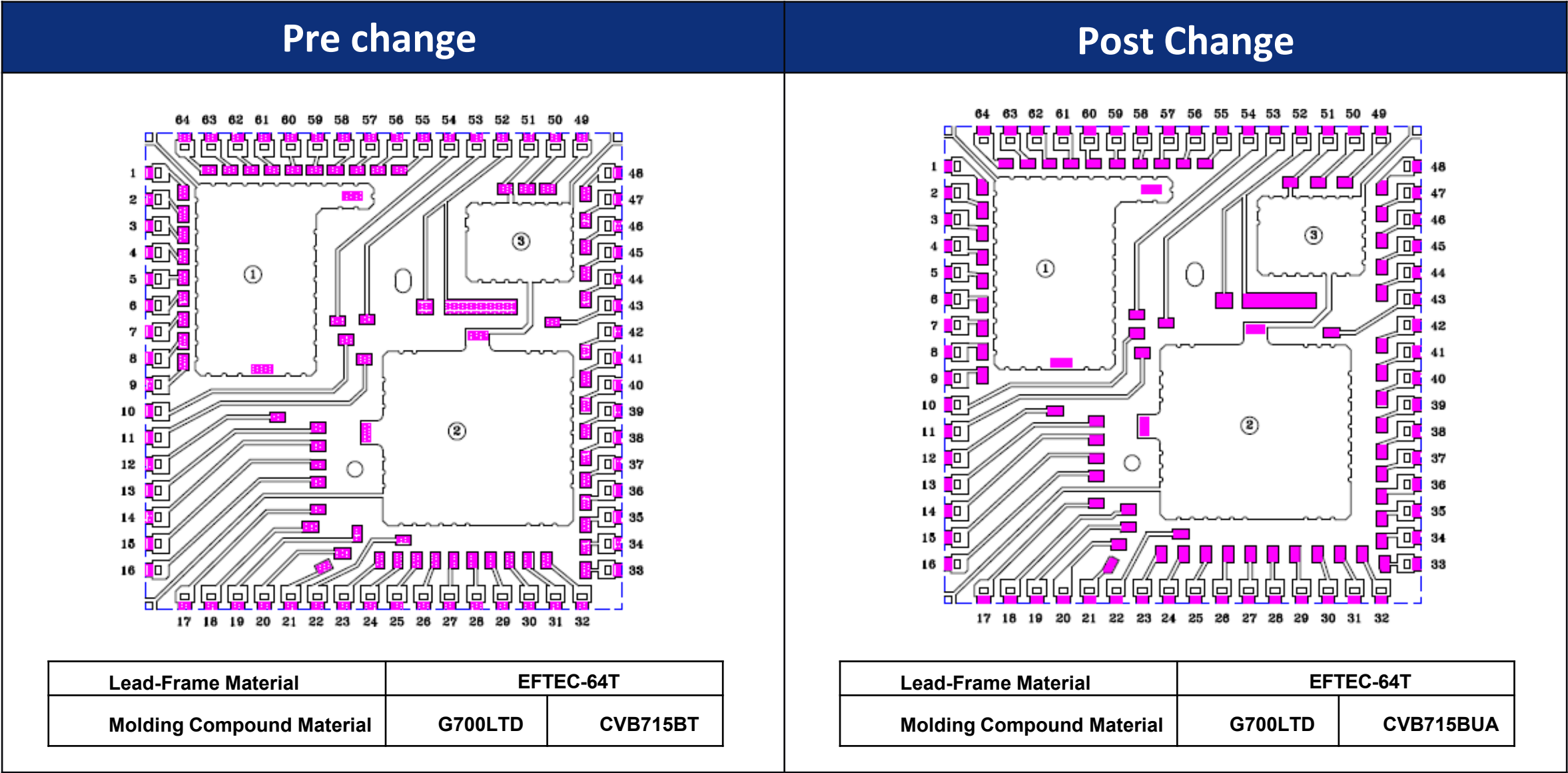


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SMART | CONNECTED | SECURE

LEAD FRAME COMPARISON



Note: Not to scale



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: CENO-02FNXL290

Date:
June 15, 2026

Qualification of CVB715BUA as a new mold compound material for selected dsPIC33CDVC256MP506 and dsPIC33CDVC128MP506 device families available in 64L VGQFN (9x9x0.927) package. This is a Grade 0 qualification.



MICROCHIP Package Qualification Report

Purpose: Qualification of CVB715BUA as a new mold compound material for selected dsPIC33CDVC256MP506 and dsPIC33CDVC128MP506 device families available in 64L VGQFN (9x9x0.927) package. This is a Grade 0 qualification.

CCB No. 7105

<u>Misc.</u>	Assembly site	NSEB
	BD Number	BD-002589 Rev 05
	MP Code (MPC)	3500M2JWAXF
	Part Number (CPN)	DSPIC33CDVC256
	Assembly Shipping Media (T/R, Tube/Tray)	Tube and T/R
<u>Lead-Frame</u>	Paddle size	90x143 MILS
	Material	EFTEC-64T
	DAP Surface Prep	Selective PPF
	Treatment	Roughened
	Process	Etched
	Lead-lock	Yes
	Part Number	F30045
	Lead Plating	PPF
<u>Bond Wire</u>	Strip Size	250x70mm
	Strip Density	120
<u>Die Attach</u>	Material	CuPdAu
	Part Number	8600
<u>MC</u>	Conductive	Yes
	Part Number	G700LTD, CVB715BUA
<u>PKG</u>	PKG Type	VGQFN-WFS
	Pin/Ball Count	64L
	PKG width/size	9x9x0.927mm



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Package Qualification Report

Manufacturing Information:

Assembly Lot ID
NSEB253600027.000
NSEB253600028.000
NSEB253600029.000

Conclusion:

Qualification of 3500M mask / DSPIC33CDVC256MP506-H/M9 product / 0.8 mil CuPdAu wire in 64L VGQFN-WFS 9x9x0.927mm package at NSEB site is qualified for MSL3 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL3: 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		



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High Temp Storage

Test Method	JESD22-A103		
Test Condition	150°C / 2000 hours		
Required Sample Size	45 units each lot / 3 lots; WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	150°C / 4000 hours		
Required Sample Size	44 units each lot / 3 lots; WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/44	0/44	0/44
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		



MICROCHIP Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 1500 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-55°C / +150°C Air to Air / 3000 Cycles		
Required Sample Size	70 units each lot / 3 lots; WBP/WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/70	0/70	0/70
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		



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Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5 Volts, 3.6 Volts		
Required Sample Size	77 units each lot / 3 lots; WBP/WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 192 hours / Bias Voltage: 5.5 Volts, 3.6 Volts		
Required Sample Size	70 units each lot / 3 lots; WBP/WBS		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/70	0/70	0/70
WBP (Fail / Pass)	0/3	0/3	0/3
WBS (Fail / Pass)	0/3	0/3	0/3
Electrical Test Tester: J750	+25°C, 85°C, 125°C and 150°C		
Result	Passed		



MICROCHIP **Package Qualification Report**

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2500853-1 NSEB253600027.000	R2500853-2 NSEB253600028.000	R2500853-3 NSEB253600029.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: J750	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 - Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 - Passed



MICROCHIP

Package Qualification Report

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 – Passed